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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	1.5KB (1K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c56-10-p



PIC16C5X

8-Bit EPROM/ROM-Based CMOS Microcontrollers

1.0 GENERAL DESCRIPTION

The PIC16C5X from Microchip Technology is a family of low cost, high performance, 8-bit fully static, EPROM/ROM-based CMOS microcontrollers. It employs a RISC architecture with only 33 single word/single cycle instructions. All instructions are single cycle except for program branches which take two cycles. The PIC16C5X delivers performance in an order of magnitude higher than its competitors in the same price category. The 12-bit wide instructions are highly symmetrical resulting in 2:1 code compression over other 8-bit microcontrollers in its class. The easy to use and easy to remember instruction set reduces development time significantly.

The PIC16C5X products are equipped with special features that reduce system cost and power requirements. The Power-on Reset (POR) and Device Reset Timer (DRT) eliminate the need for external RESET circuitry. There are four oscillator configurations to choose from, including the power saving LP (Low Power) oscillator and cost saving RC oscillator. Power saving SLEEP mode, Watchdog Timer and Code Protection features improve system cost, power and reliability.

The UV erasable Cerdip packaged versions are ideal for code development, while the cost effective One Time Programmable (OTP) versions are suitable for production in any volume. The customer can take full advantage of Microchip's price leadership in OTP microcontrollers, while benefiting from the OTP's flexibility.

The PIC16C5X products are supported by a full featured macro assembler, a software simulator, an in-circuit emulator, a low cost development programmer and a full featured programmer. All the tools are supported on IBM® PC and compatible machines.

1.1 Applications

The PIC16C5X series fits perfectly in applications ranging from high speed automotive and appliance motor control to low power remote transmitters/receivers, pointing devices and telecom processors. The EPROM technology makes customizing application programs (transmitter codes, motor speeds, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages, for through hole or surface mounting, make this microcontroller series perfect for applications with space limitations. Low cost, low power, high performance ease of use and I/O flexibility make the PIC16C5X series very versatile even in areas where no microcontroller use has been considered before (e.g., timer functions, replacement of "glue" logic in larger systems, co-processor applications).

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TABLE 3-2: PINOUT DESCRIPTION - PIC16C55, PIC16C57, PIC16CR57

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0	6	6	5	I/O	TTL	Bi-directional I/O port
RA1	7	7	6	I/O	TTL	
RA2	8	8	7	I/O	TTL	
RA3	9	9	8	I/O	TTL	
RB0	10	10	9	I/O	TTL	Bi-directional I/O port
RB1	11	11	10	I/O	TTL	
RB2	12	12	11	I/O	TTL	
RB3	13	13	12	I/O	TTL	
RB4	14	14	13	I/O	TTL	
RB5	15	15	15	I/O	TTL	
RB6	16	16	16	I/O	TTL	
RB7	17	17	17	I/O	TTL	
RC0	18	18	18	I/O	TTL	Bi-directional I/O port
RC1	19	19	19	I/O	TTL	
RC2	20	20	20	I/O	TTL	
RC3	21	21	21	I/O	TTL	
RC4	22	22	22	I/O	TTL	
RC5	23	23	23	I/O	TTL	
RC6	24	24	24	I/O	TTL	
RC7	25	25	25	I/O	TTL	
T0CKI	1	1	2	I	ST	Clock input to Timer0. Must be tied to Vss or VDD, if not in use, to reduce current consumption.
$\overline{\text{MCLR}}$	28	28	28	I	ST	Master clear (RESET) input. This pin is an active low RESET to the device.
OSC1/CLKIN	27	27	27	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	26	26	26	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
VDD	2	2	3,4	P	—	Positive supply for logic and I/O pins.
Vss	4	4	1,14	P	—	Ground reference for logic and I/O pins.
N/C	3,5	3,5	—	—	—	Unused, do not connect.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

4.0 OSCILLATOR CONFIGURATIONS

4.1 Oscillator Types

PIC16C5Xs can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

1. LP: Low Power Crystal
2. XT: Crystal/Resonator
3. HS: High Speed Crystal/Resonator
4. RC: Resistor/Capacitor

Note: Not all oscillator selections available for all parts. See Section 9.1.

4.2 Crystal Oscillator/Ceramic Resonators

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 4-1). The PIC16C5X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source drive the OSC1/CLKIN pin (Figure 4-2).

FIGURE 4-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)

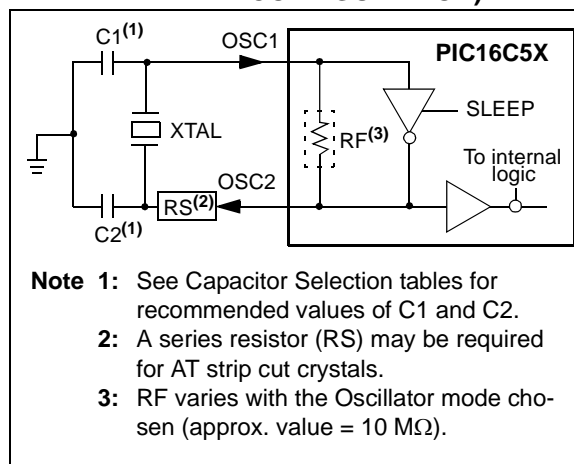


FIGURE 4-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

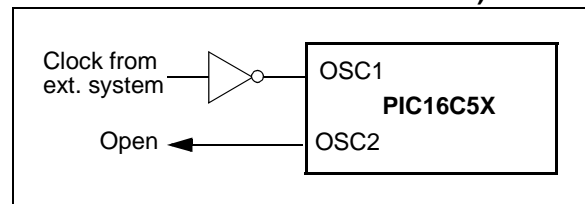


TABLE 4-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS - PIC16C5X, PIC16CR5X

Osc Type	Resonator Freq	Cap. Range C1	Cap. Range C2
XT	455 kHz	68-100 pF	68-100 pF
	2.0 MHz	15-33 pF	15-33 pF
	4.0 MHz	10-22 pF	10-22 pF
HS	8.0 MHz	10-22 pF	10-22 pF
	16.0 MHz	10 pF	10 pF

These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 4-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR - PIC16C5X, PIC16CR5X

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz ⁽¹⁾	15 pF	15 pF
XT	100 kHz	15-30 pF	200-300 pF
	200 kHz	15-30 pF	100-200 pF
	455 kHz	15-30 pF	15-100 pF
	1 MHz	15-30 pF	15-30 pF
	2 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15 pF	15 pF
	20 MHz	15 pF	15 pF

Note 1: For VDD > 4.5V, C1 = C2 ≈ 30 pF is recommended.

These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

Note: If you change from this device to another device, please verify oscillator characteristics in your application.

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9.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits that deal with the needs of real-time applications. The PIC16C5X family of microcontrollers have a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These features are:

- Oscillator Selection (Section 4.0)
- RESET (Section 5.0)
- Power-On Reset (Section 5.1)
- Device Reset Timer (Section 5.2)
- Watchdog Timer (WDT) (Section 9.2)
- SLEEP (Section 9.3)
- Code protection (Section 9.4)
- ID locations (Section 9.5)

The PIC16C5X Family has a Watchdog Timer which can be shut off only through configuration bit WDTE. It runs off of its own RC oscillator for added reliability. There is an 18 ms delay provided by the Device Reset Timer (DRT), intended to keep the chip in RESET until the crystal oscillator is stable. With this timer on-chip, most applications need no external RESET circuitry.

The SLEEP mode is designed to offer a very low current Power-down mode. The user can wake up from SLEEP through external RESET or through a Watchdog Timer time-out. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

ADDWF Add W and f

Syntax: [*label*] ADDWF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(W) + (f) \rightarrow (\text{dest})$

Status Affected: C, DC, Z

Encoding:

0001	11df	ffff
------	------	------

Description: Add the contents of the W register and register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: ADDWF TEMP_REG, 0

Before Instruction

W = 0x17

TEMP_REG = 0xC2

After Instruction

W = 0xD9

TEMP_REG = 0xC2

ANDWF AND W with f

Syntax: [*label*] ANDWF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(W) .\text{AND.} (f) \rightarrow (\text{dest})$

Status Affected: Z

Encoding:

0001	01df	ffff
------	------	------

Description: The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: ANDWF TEMP_REG, 1

Before Instruction

W = 0x17

TEMP_REG = 0xC2

After Instruction

W = 0x17

TEMP_REG = 0x02

ANDLW AND literal with W

Syntax: [*label*] ANDLW k

Operands: $0 \leq k \leq 255$

Operation: $(W) .\text{AND.} (k) \rightarrow (W)$

Status Affected: Z

Encoding:

1110	kkkk	kkkk
------	------	------

Description: The contents of the W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example: ANDLW H'5F'

Before Instruction

W = 0xA3

After Instruction

W = 0x03

BCF Bit Clear f

Syntax: [*label*] BCF f,b

Operands: $0 \leq f \leq 31$
 $0 \leq b \leq 7$

Operation: $0 \rightarrow (f)$

Status Affected: None

Encoding:

0100	bbbf	ffff
------	------	------

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Example: BCF FLAG_REG, 7

Before Instruction

FLAG_REG = 0xC7

After Instruction

FLAG_REG = 0x47

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12.1 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial)

PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial)			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ Ta ≤ +70°C for commercial				
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage					
		PIC16C5X-RC	3.0	—	6.25	V	
		PIC16C5X-XT	3.0	—	6.25	V	
		PIC16C5X-10	4.5	—	5.5	V	
		PIC16C5X-HS	4.5	—	5.5	V	
		PIC16C5X-LP	2.5	—	6.25	V	
D002	VDR	RAM Data Retention Voltage⁽¹⁾		1.5*	—	V	Device in SLEEP Mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset		VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current⁽²⁾					
		PIC16C5X-RC ⁽³⁾	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V
		PIC16C5X-XT	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V
		PIC16C5X-10	—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V
		PIC16C5X-HS	—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V
		PIC16C5X-HS	—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V
		PIC16C5X-LP	—	15	32	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020	IPD	Power-down Current⁽²⁾	—	4.0	12	μA	VDD = 3.0V, WDT enabled
			—	0.6	9	μA	VDD = 3.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

13.3 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	VIL	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	VSS VSS VSS VSS VSS	— — — — —	0.2 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.15 VDD	V V V V V	Pin at hi-impedance RC mode only ⁽³⁾ XT, HS and LP modes
D040	VIH	Input High Voltage I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	2.0 0.6 VDD 0.85 VDD 0.85 VDD 0.85 VDD 0.85 VDD	— — — — — —	VDD VDD VDD VDD VDD VDD	V V V V V V	VDD = 3.0V to 5.5V ⁽⁴⁾ Full VDD range ⁽⁴⁾ RC mode only ⁽³⁾ XT, HS and LP modes
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 VDD*	—	—	V	
D060	IIL	Input Leakage Current^(1,2) I/O ports MCLR MCLR T0CKI OSC1	–1.0 –5.0 — –3.0 –3.0	— — 0.5 0.5 0.5	+1.0 — +5.0 +3.0 +3.0	μA μA μA μA μA	For VDD ≤ 5.5V: VSS ≤ VPIN ≤ VDD, pin at hi-impedance VPIN = VSS + 0.25V VPIN = VDD VSS ≤ VPIN ≤ VDD VSS ≤ VPIN ≤ VDD, XT, HS and LP modes
D080	VOL	Output Low Voltage I/O ports OSC2/CLKOUT	— —	— —	0.5 0.5	V V	IOL = 10 mA, VDD = 6.0V IOL = 1.9 mA, VDD = 6.0V, RC mode only
D090	VOH	Output High Voltage⁽²⁾ I/O ports OSC2/CLKOUT	VDD – 0.5 VDD – 0.5	— —	— —	V V	IOH = –4.0 mA, VDD = 6.0V IOH = –0.8 mA, VDD = 6.0V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

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13.4 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified)				
			Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	V _{IL}	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	V _{SS} V _{SS} V _{SS} V _{SS} V _{SS}	— — — — —	0.15 V _{DD} 0.15 V _{DD} 0.15 V _{DD} 0.15 V _{DD} 0.3 V _{DD}	V V V V V	Pin at hi-impedance RC mode only ⁽³⁾ XT, HS and LP modes
D040	V _{IH}	Input High Voltage I/O ports I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	0.45 V _{DD} 2.0 0.36 V _{DD} 0.85 V _{DD} 0.85 V _{DD} 0.85 V _{DD} 0.7 V _{DD}	— — — — — — —	V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD} V _{DD}	V V V V V V V	For all V _{DD} ⁽⁴⁾ 4.0V < V _{DD} ≤ 5.5V ⁽⁴⁾ V _{DD} > 5.5V RC mode only ⁽³⁾ XT, HS and LP modes
D050	V _{HYS}	Hysteresis of Schmitt Trigger inputs	0.15 V _{DD} *	—	—	V	
D060	I _{IL}	Input Leakage Current^(1,2) I/O ports MCLR MCLR T0CKI OSC1	−1.0 −5.0 — −3.0 −3.0	0.5 — 0.5 0.5 0.5	+1.0 — +5.0 +3.0 +3.0	μA μA μA μA μA	For V_{DD} ≤ 5.5V: V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance V _{PIN} = V _{SS} + 0.25V V _{PIN} = V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT, HS and LP modes
D080	V _{OL}	Output Low Voltage I/O ports OSC2/CLKOUT	— —	— —	0.6 0.6	V V	I _{OL} = 8.7 mA, V _{DD} = 4.5V I _{OL} = 1.6 mA, V _{DD} = 4.5V, RC mode only
D090	V _{OH}	Output High Voltage⁽²⁾ I/O ports OSC2/CLKOUT	V _{DD} − 0.7 V _{DD} − 0.7	— —	— —	V V	I _{OH} = −5.4 mA, V _{DD} = 4.5V I _{OH} = −1.0 mA, V _{DD} = 4.5V, RC mode only

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

PIC16C5X

FIGURE 14-11: V_{TH} (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (XT, HS, AND LP MODES) vs. V_{DD}

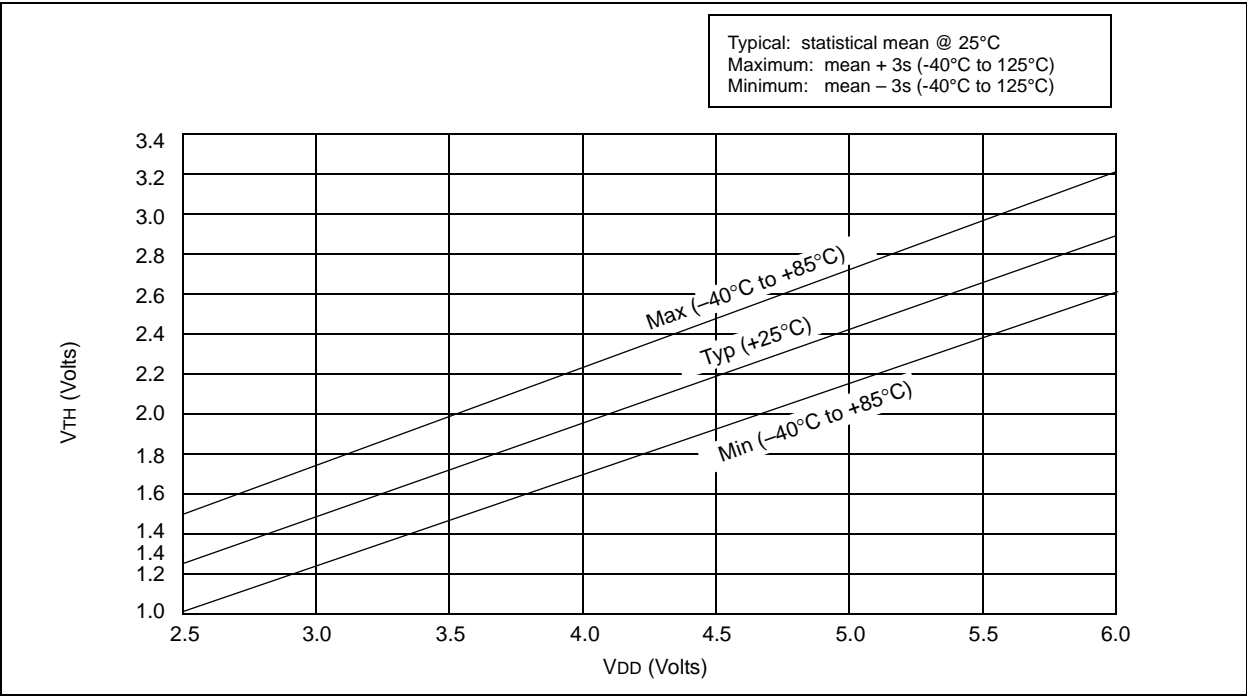


FIGURE 14-12: TYPICAL I_{DD} VS. FREQUENCY (EXTERNAL CLOCK, 25°C)

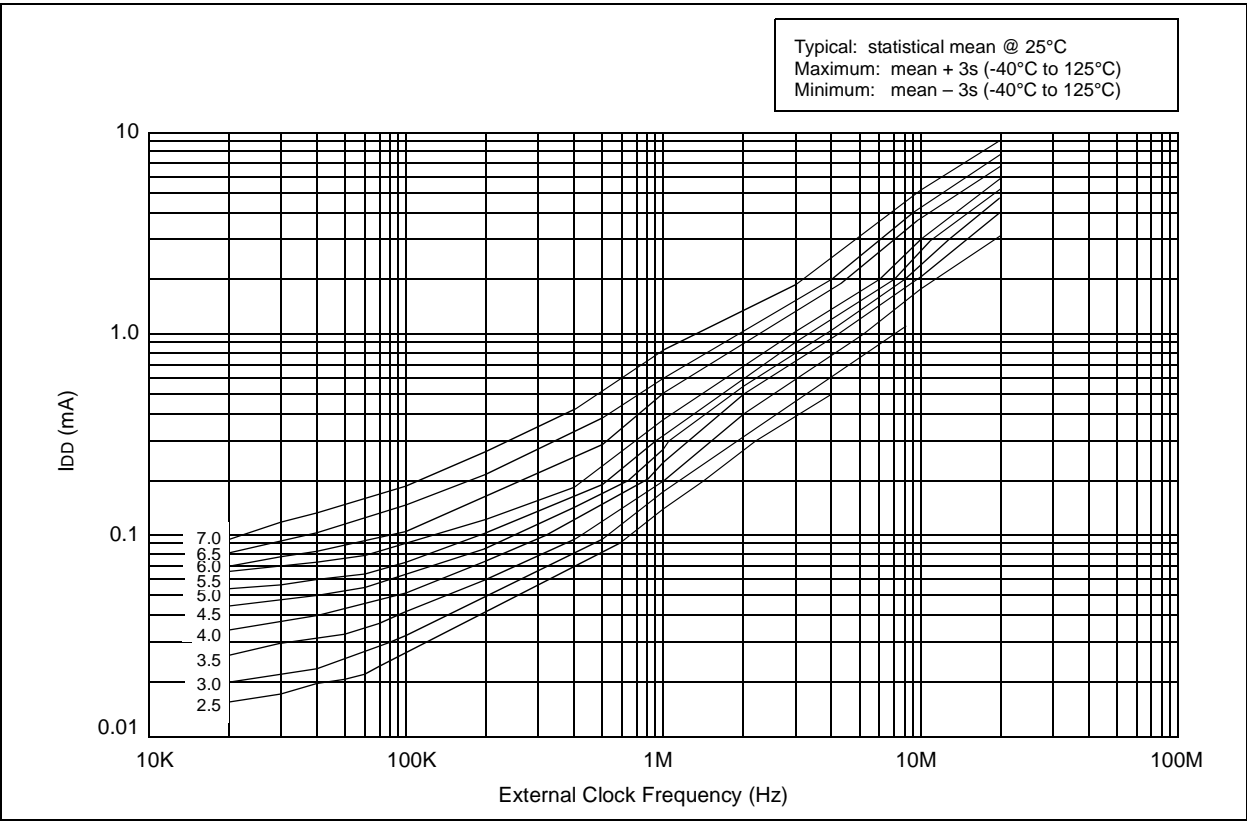


FIGURE 14-17: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD

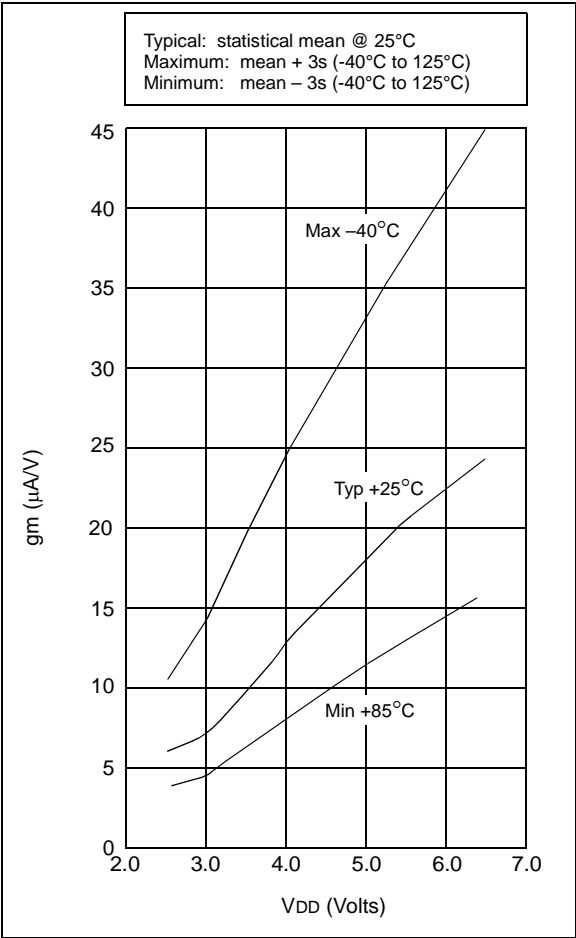
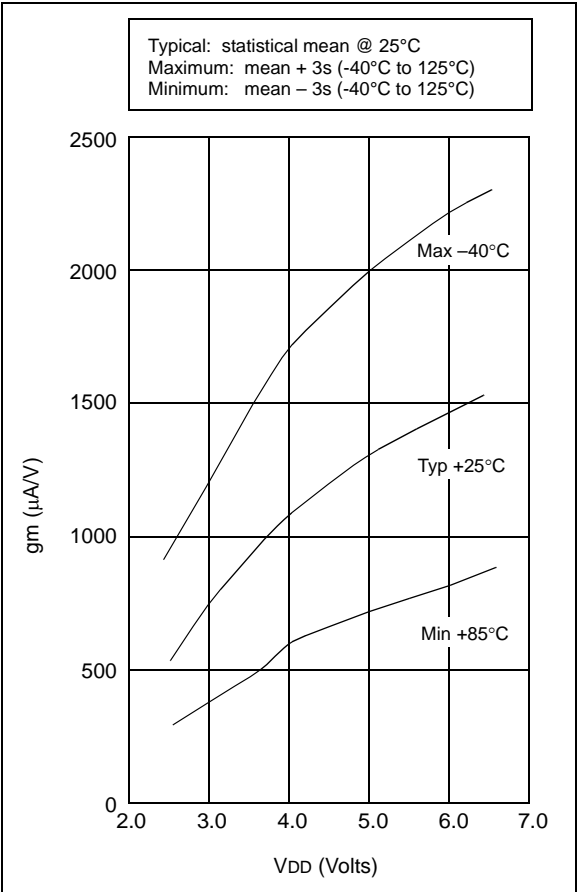


FIGURE 14-18: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



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15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16C54A-04E, 10E, 20E (Extended)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage					
		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.5 4.5	— —	5.5 5.5	V V	RC and XT modes HS mode
D002	VDR	RAM Data Retention Voltage⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current⁽²⁾					
		PIC16LC54A	—	0.5	25	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
			—	11	27	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	11	35	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
			—	11	37	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Extended
D010A		PIC16C54A	—	1.8	3.3	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
			—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

Note 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

Note 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

15.6 Timing Diagrams and Specifications

FIGURE 15-2: EXTERNAL CLOCK TIMING - PIC16C54A

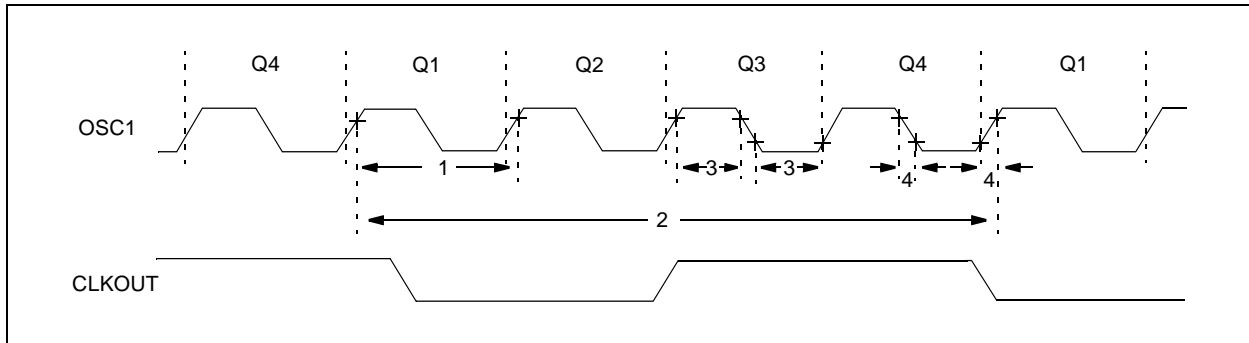


TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54A

Standard Operating Conditions (unless otherwise specified)							
AC Characteristics							
Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -20°C ≤ TA ≤ +85°C for industrial - PIC16LV54A-02I -40°C ≤ TA ≤ +125°C for extended							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
	FOSC	External CLKIN Frequency ⁽¹⁾	DC	—	4.0	MHz	XT osc mode
			DC	—	2.0	MHz	XT osc mode (PIC16LV54A)
			DC	—	4.0	MHz	HS osc mode (04)
			DC	—	10	MHz	HS osc mode (10)
			DC	—	20	MHz	HS osc mode (20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency ⁽¹⁾	DC	—	4.0	MHz	RC osc mode
			DC	—	2.0	MHz	RC osc mode (PIC16LV54A)
			0.1	—	4.0	MHz	XT osc mode
			0.1	—	2.0	MHz	XT osc mode (PIC16LV54A)
			4.0	—	4.0	MHz	HS osc mode (04)
			4.0	—	10	MHz	HS osc mode (10)
			4.0	—	20	MHz	HS osc mode (20)
			5.0	—	200	kHz	LP osc mode

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

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FIGURE 16-12: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 pF, 25°C)

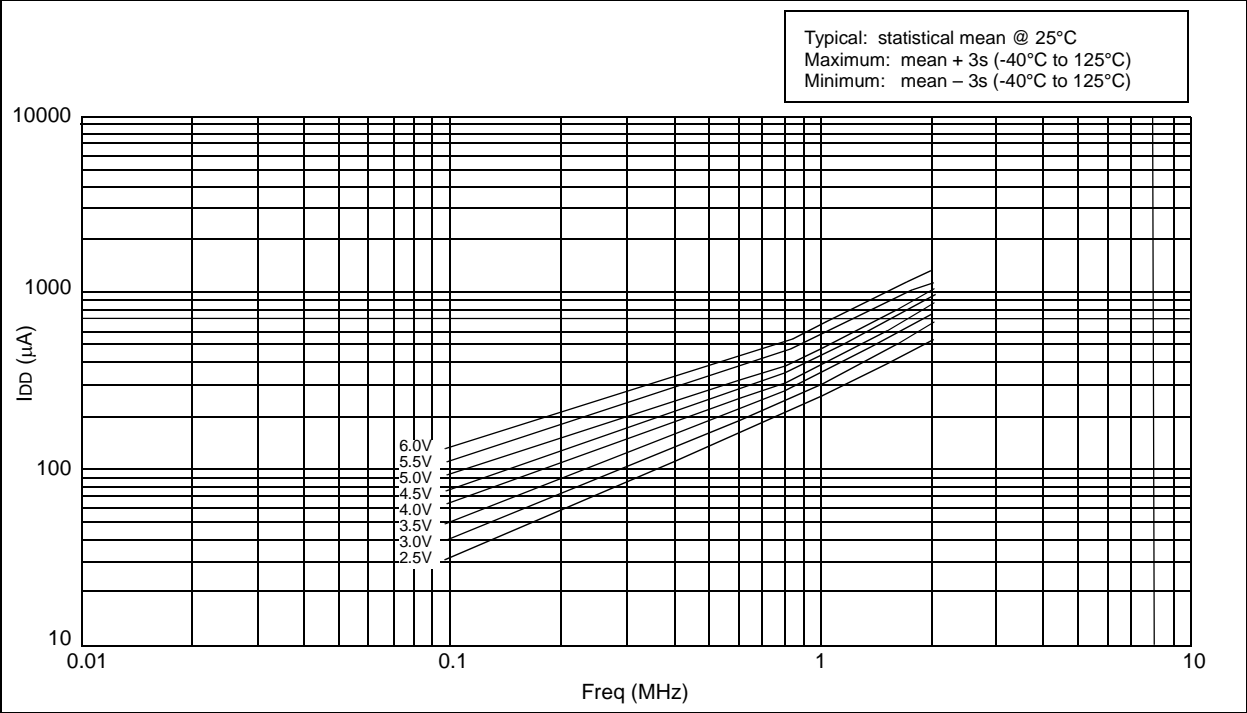
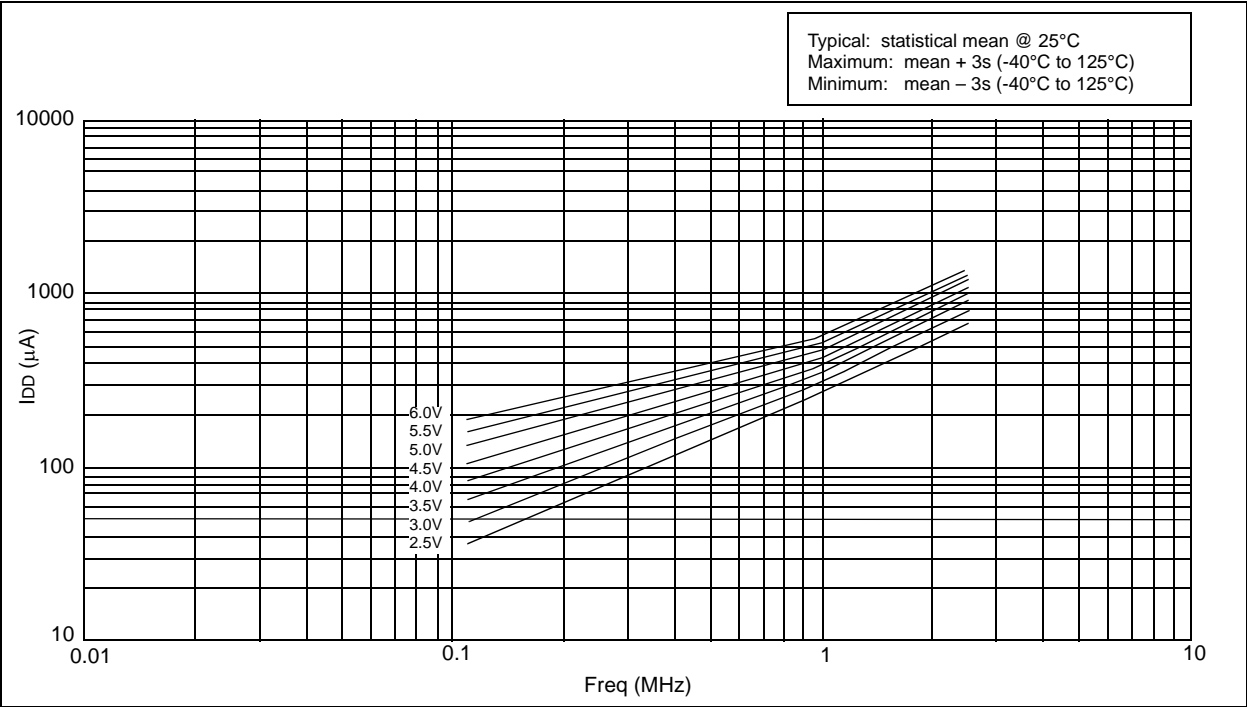


FIGURE 16-13: MAXIMUM I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 pF, -40°C to +85°C)



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19.2 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-40 (Commercial)⁽¹⁾

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified)				
			Operating Temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D030	VIL	Input Low Voltage I/O Ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1	VSS VSS VSS VSS	— — — —	0.8 0.15 VDD 0.15 VDD 0.2 VDD	V V V V	4.5V < VDD ≤ 5.5V HS, 20 MHz ≤ FOSC ≤ 40 MHz
D040	VIH	Input High Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1	2.0 0.85 VDD 0.85 VDD 0.8 VDD	— — — —	VDD VDD VDD VDD	V V V V	4.5V < VDD ≤ 5.5V HS, 20 MHz ≤ FOSC ≤ 40 MHz
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 VDD*	—	—	V	
D060	IIL	Input Leakage Current^(2,3) I/O ports MCLR MCLR T0CKI OSC1	-1.0 -5.0 — -3.0 -3.0	0.5 — 0.5 0.5 0.5	+1.0 +5.0 +3.0 +3.0 —	μA μA μA μA μA	For VDD ≤ 5.5V: VSS ≤ VPIN ≤ VDD, pin at hi-impedance VPIN = VSS + 0.25V VPIN = VDD VSS ≤ VPIN ≤ VDD VSS ≤ VPIN ≤ VDD, HS
D080	VOL	Output Low Voltage I/O ports	—	—	0.6	V	IOL = 8.7 mA, VDD = 4.5V
D090	VOH	Output High Voltage⁽³⁾ I/O ports	VDD - 0.7	—	—	V	IOH = -5.4 mA, VDD = 4.5V

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- Note 1:** Device operation between 20 MHz to 40 MHz requires the following: VDD between 4.5V to 5.5V, OSC1 pin externally driven, OSC2 pin not connected and HS oscillator mode and commercial temperatures. For operation between DC and 20 MHz, See Section 17.3.
- 2:** The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.
- 3:** Negative current is defined as coming out of the pin.

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FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40

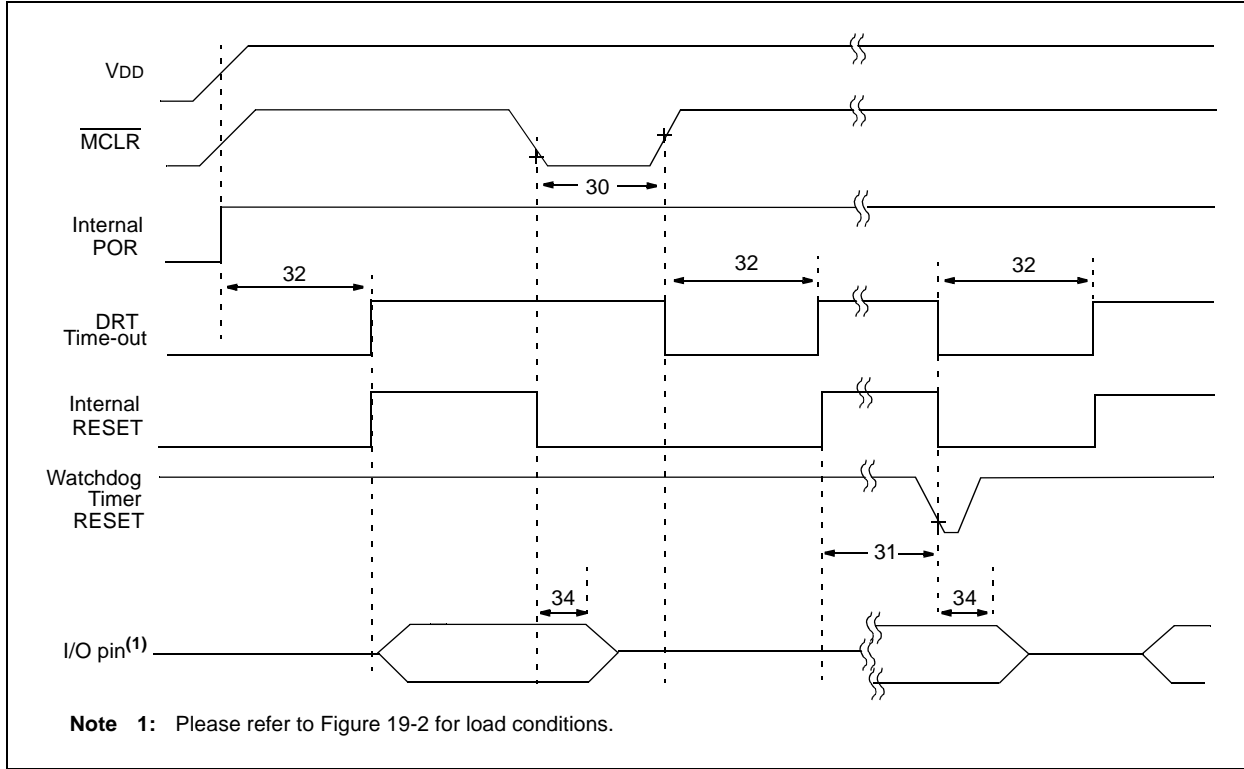


TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

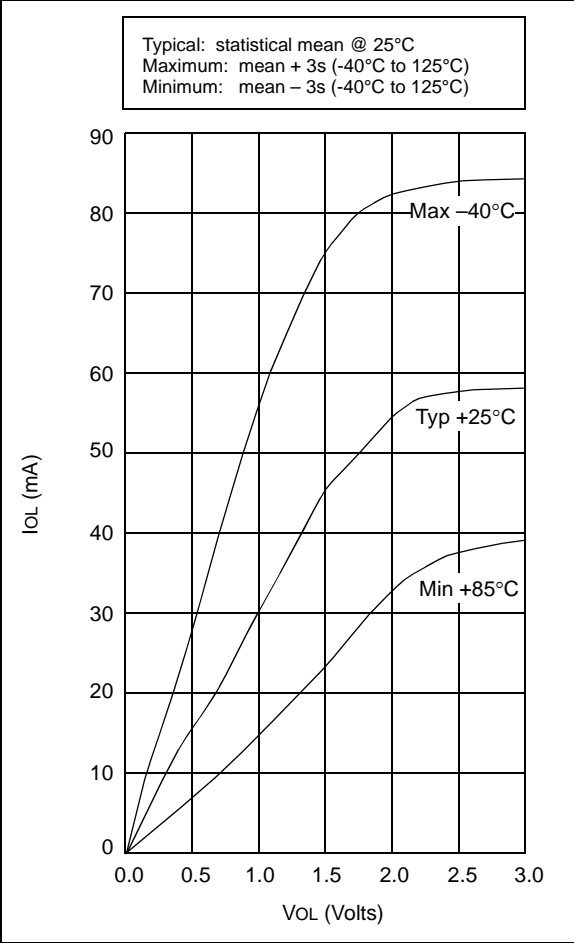
Standard Operating Conditions (unless otherwise specified)							
AC Characteristics							
Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ (commercial)							
Operating Voltage VDD range is described in Section 19.1.							
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
30	Tmcl	MCLR Pulse Width (low)	1000*	—	—	ns	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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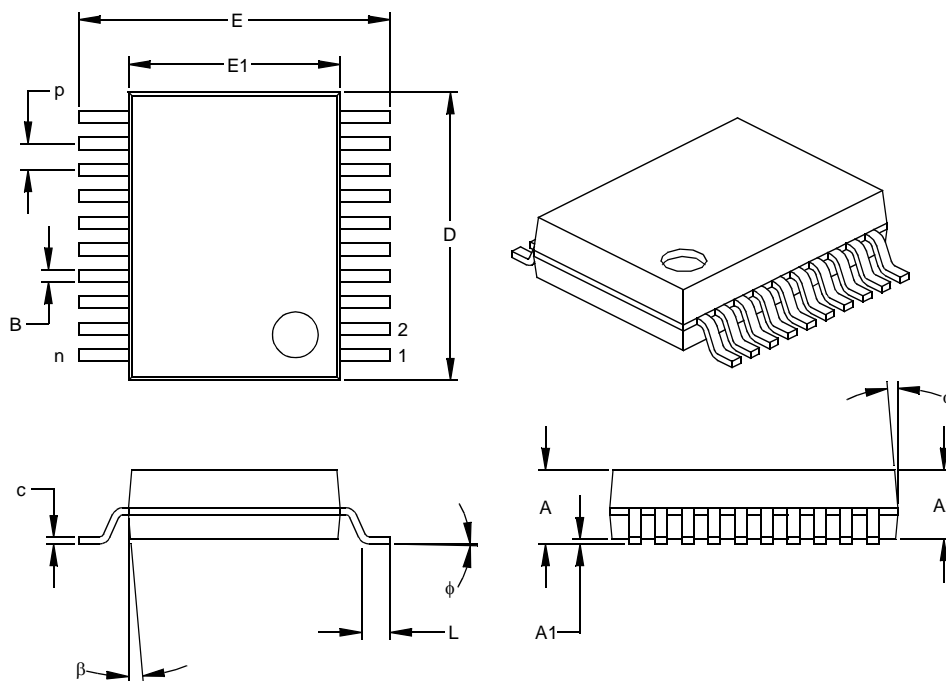
FIGURE 20-9: I_{OL} vs. V_{OL} , $V_{DD} = 5\text{ V}$



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20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-150

Drawing No. C04-072

APPENDIX A: COMPATIBILITY

To convert code written for PIC16CXX to PIC16C5X, the user should take the following steps:

1. Check any `CALL`, `GOTO` or instructions that modify the PC to determine if any program memory page select operations (PA2, PA1, PA0 bits) need to be made.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any special function register page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change RESET vector to proper value for processor used.
6. Remove any use of the `ADDLW`, `RETURN` and `SUBLW` instructions.
7. Rewrite any code segments that use interrupts.

APPENDIX B: REVISION HISTORY

Revision KE (January 2013)

Added a note to each package outline drawing.